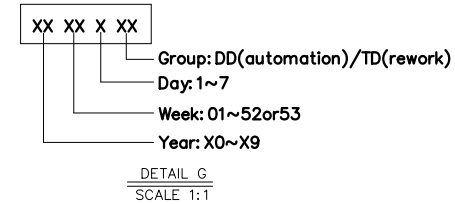
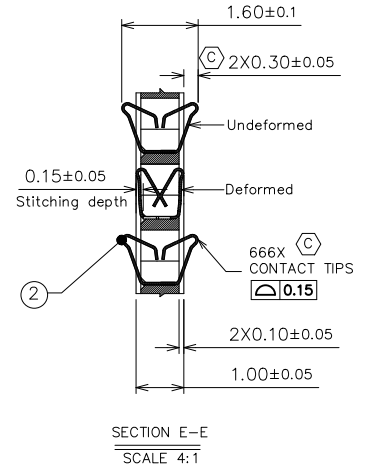
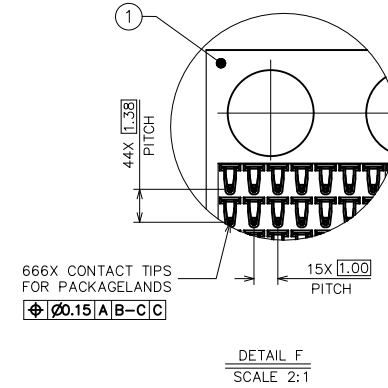
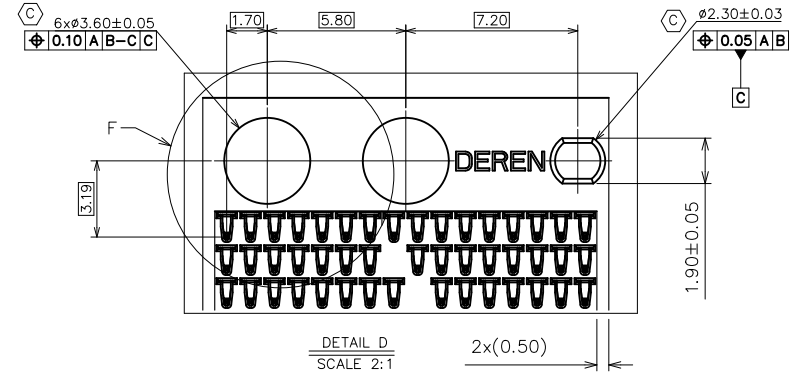
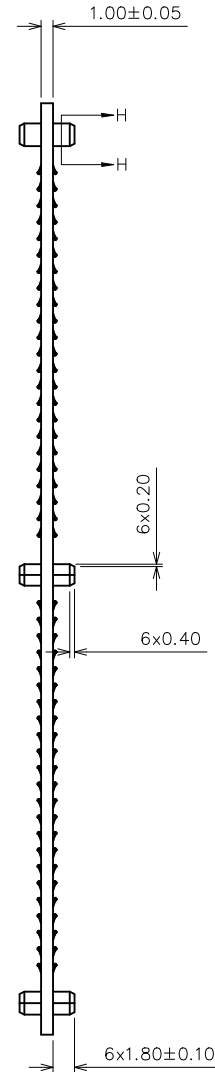
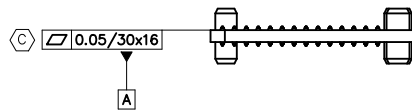
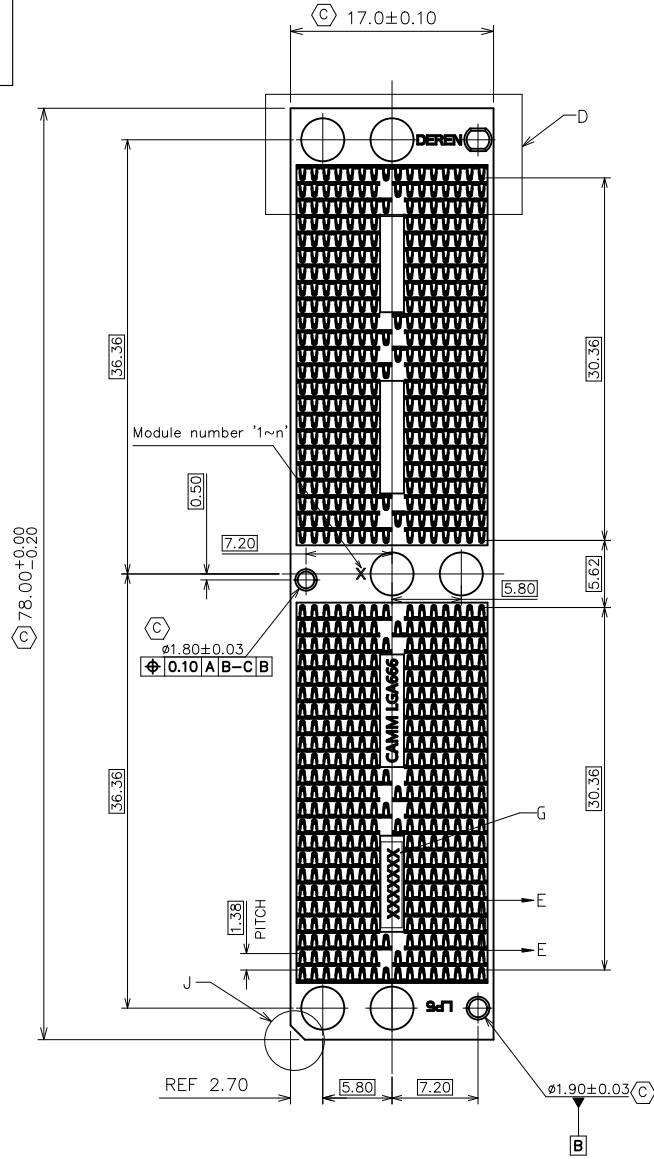


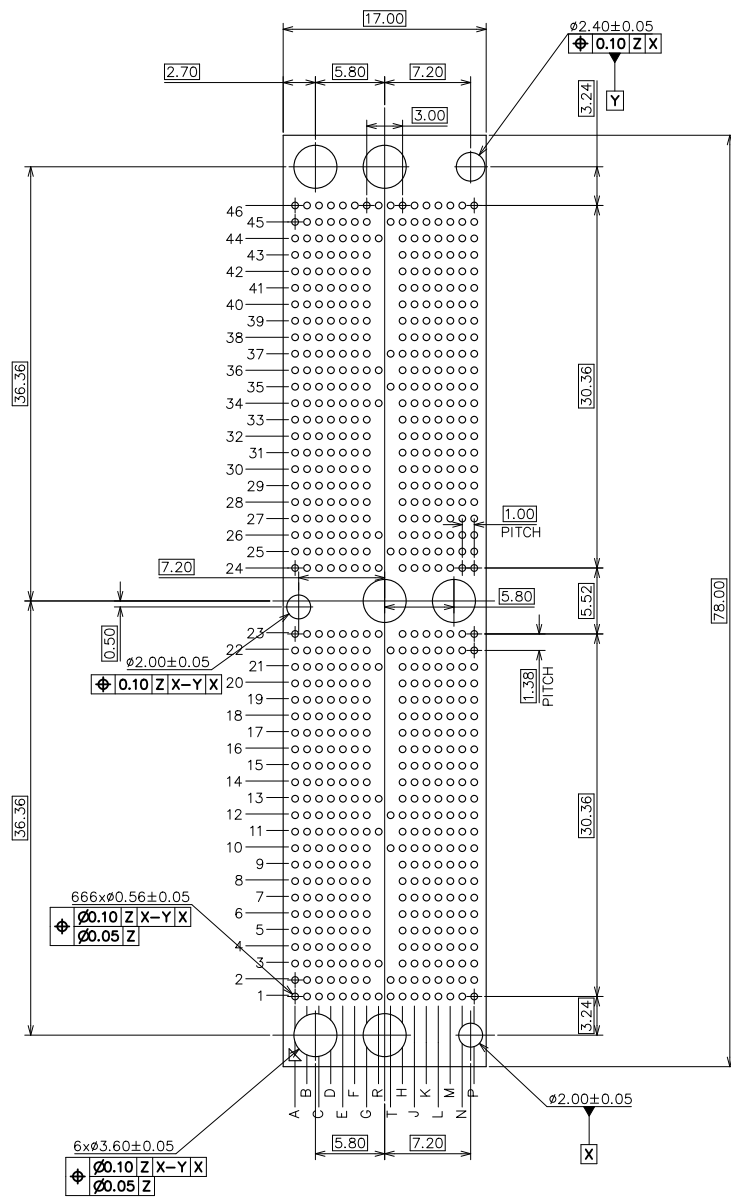
HF

Halogen Free



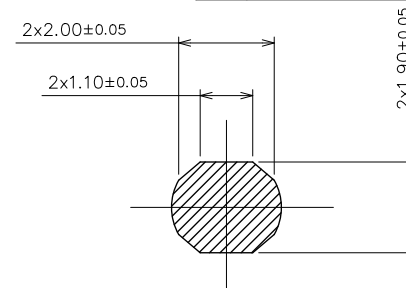
ASSEMBLY COMPONENT LIST			DIM	TOL	DIM	TOL	DEREN			
ITEMS	PART NAME	QT'Y	.X	±0.30	.X	±2°	SHENZHEN DEREN ELECTRONIC CO., LTD			
1	HOUSING	1	.XX	±0.20			C-DWG: / DATE: 09,07,24			
2	CONTACT	666					DESIGN: Robin			
							CHECK: Kenneth			
							APPROVAL: Andy			
							TITLE: LPD08S CAMM CONNECTOR LGA666 ASSEMBLY			
							P/N: SEE TABLE A			
							SHEET: 1/3			
							SCALE: 1:1			
							UNIT: mm			

Halogen Free

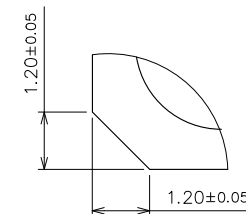


REFERENCE PATTERN LAYOUT

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			INITIAL RELEASE	09/07'2024	Robin



SECTION H-H
SCALE 4:1



DETAIL J

SCALE 4:1

NOTES :

PRODUCT MUST MEET CONTROLLED SUBSTANCES SPEC. ROHS 2.0

1. MATERIAL :

1.1 HOUSING: LCP, UL94V-0, COLOR: BLACK.

1.2 CONTACTS: COPPER ALLOY.

2. FINISH:

CONTACT: Au PLATING ON CONTACT AREA (SEE TABLE A).

[50u~100u"] NICKEL UNDERPLATING OVERALL.

3. CTF DIMENSION(CRITICAL TO FUNCTION) BY INTEL:

4. PRODUCT MUST MEET THE SPECIFICATION.

TABLE A:

4	56L6C5-004H	TBD	CONTACT	GOLD FLASH, Ni: 50u~100u".
			HOUSING	LCP UL94V-0,BLACK
3	56L6C5-003H	TBD	CONTACT	Au: 10u", Ni: 50u~100u".
			HOUSING	LCP UL94V-0,BLACK
2	56L6C5-002H	TBD	CONTACT	Au: 15u", Ni: 50u~100u".
			HOUSING	LCP UL94V-0,BLACK
1	56L6C5-001H	TBD	CONTACT	Au: 30u", Ni: 50u~100u".
			HOUSING	LCP UL94V-0,BLACK
ITEM NO.	DEREN P/N	CUSTOMER P/N	COMPONENT	SPECIFICATION

DIM	TOL	DIM	TOL		DEREN					
X.	±0.30	X.	±2°		SHENZHEN DEREN ELECTRONIC CO.,LTD					
.X	±0.25	.X	±1°		C-DWG:		DATE	TITLE: LPDDR5 CANM CONNECTOR LGA666 ASSEMBLY		
.XX	±0.20				DESIGN:	Robin	09,07,24	P/N: SEE TABLE A		
				DRAW NO.	CHECK:	Kenneth	09,07,24	SHEET:	2/3	
				SC2410288						
				REV.	X1	APPROVAL:	Andy	09,07,24	SCALE:	1:1 UNIT: mm